

The Florida Building Material Alliance

Terrence Eagan Lewis Scholarship Fund

Follow four simple steps to be considered for FBMA's annual Terrence Eagan Lewis Scholarship. Our scholarship form, eligibility requirements and application procedures are provided in this document. Apply to FBMA by August 11, 2023 to see if you qualify! If you have any questions regarding this scholarship, please contact:

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Director of Operations
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Mount Dora, FL 32756
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Fax: (352) 383-8756
email: Betty@fbma.org



Terrence Eagan Lewis Scholarship - \$2,500

Bonnie Lewis and family established the Terrence Eagan Lewis Scholarship in 2003, after accumulating \$12,000 from memorial donations and gifts received on Terry's behalf.

Terrence Eagan Lewis was Co-Founder of BonTEL Fastener Corporation, located in Pinellas Park, Florida.

This scholarship is generously supported by FBMA member contributions and other gifts. Please contact FBMA today if you would like to donate to this scholarship fund.



Applying for the Terrence Eagan Lewis Scholarship Fund

Eligibility Requirements

In order to be considered, you must follow these four steps and mail your application by August 11, 2023.

Step 1: Complete and sign Part A of the Application Form.

Step 2: Write a personal statement (a maximum of two type written pages). A resume may be included, but is not required.

Step 3: Submit your most recent academic transcript(s). If this will be your first semester enrolled in college, a copy of your high school diploma (or GED equivalency) must be submitted as well.

Step 4: Include a photograph for publication (this will not be seen by the selection committee, but rather FBMA staff).

Decision Making Process

The Scholarship Selection Committee, who is composed of no less than five FBMA Education Committee members, has the authority to select recipients based on the qualifications and merits of the applicants and will be the governing body in determining the award.

The Terrence Eagan Lewis Scholarship is intended to encourage and support capable students who have graduated from high school or have obtained a GED; are an employee or immediate family member (mother, father, daughter, son or individual living in the same household) of an employer who is currently a member of FBMA; and enrolled in a 2 or 4 year accredited college, studying architecture, engineering, business management or another applicable program relevant to the building materials industry.

Information is drawn from your application, transcript and personal statement.

The Scholarship Selection Committee considers a variety of factors including: Academic Achievement, Grades and Courses Selected.

Interest in the Field: Knowledge of the building materials industry, demonstrated interest through activities/jobs, potential for related career.

Personal Qualities: Motivation, Values, Maturity and Goals.



The Florida Building Material Association

Terrence Eagan Lewis 2023 Scholarship Fund Application

Part A: Fill out completely. Please TYPE or PRINT clearly in black or blue ink. All materials must be submitted in English.

Ms. Mrs. Mr. Full Name:

Indicate preferred address for contact and mailing:

Address

City ST Zip Code

Telephone Email

Student Account Number

High School Name

Address

City ST Zip Code

Telephone Email

College or University Name

Address

City ST Zip Code

Telephone Email

Fall 2022 Class Standing: 1st year 2nd year 3rd year 4th year

Expected Graduation Date (Month/Year): Current GPA

Major/StudyConcentration:

Employment Experience (resume may be attached):

Attach a personal essay, describing your career plans, long-range aspirations, special achievements and honors, employment experience, and any other special skills. (Maximum of two type written pages).

Hand written essays will not be accepted.

Submit academic transcripts and complete attached form listing titles of all currently enrolled classes for the fall.

Attach a photograph to be used for publication of award winners. Photograph will not be part of the selection process.

Please sign below if this application is complete and accurate:

Signature: _____

Date:

Please list titles of all currently enrolled courses (include course descriptions):

Course Listings:

THIS APPLICATION MUST BE POSTMARKED BY August 11, 2023.

Send completed application with attachments to:

FBMA, Attention: 2023 Scholarship Selection Committee, PO Box 65, Mount Dora, FL
32756